

N-channel 600 V, 0.078  $\Omega$  typ., 34 A MDmesh M2 Power MOSFETs in D<sup>2</sup>PAK, TO-220 and TO-247 packages

Datasheet – production data

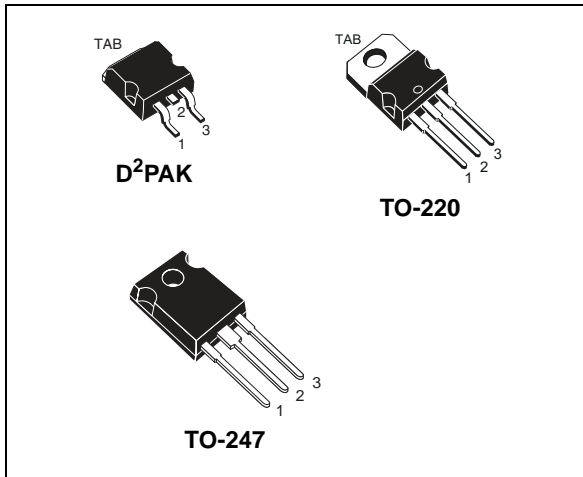
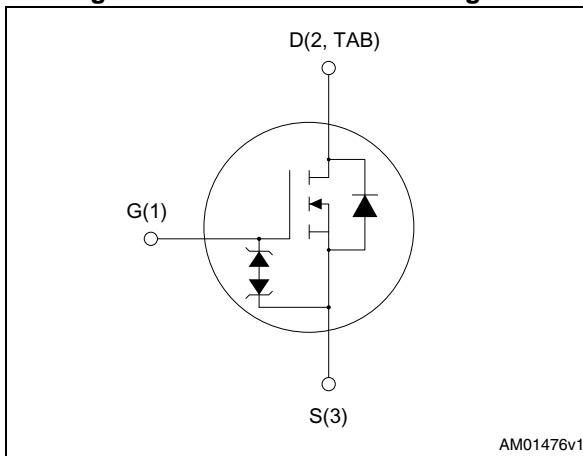


Figure 1. Internal schematic diagram



## Features

Order code	$V_{DS} @ T_{Jmax}$	$R_{DS(on) max}$	$I_D$
STB40N60M2	650 V	0.088 $\Omega$	34 A
STP40N60M2			
STW40N60M2			

- Extremely low gate charge
- Excellent output capacitance ( $C_{oss}$ ) profile
- 100% avalanche tested
- Zener-protected

## Applications

- Switching applications
- LLC converters, resonant converters

## Description

These devices are N-channel Power MOSFETs developed using MDmesh™ M2 technology. Thanks to their strip layout and improved vertical structure, the devices exhibit low on-resistance and optimized switching characteristics, rendering them suitable for the most demanding high efficiency converters.

Table 1. Device summary

Order code	Marking	Packages	Packing
STB40N60M2	40N60M2	D <sup>2</sup> PAK	Tape and reel
STP40N60M2		TO-220	Tube
STW40N60M2		TO-247	

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	34	A
$I_D$	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	22	A
$I_{DM}^{(1)}$	Drain current (pulsed)	136	A
$P_{TOT}$	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	250	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	15	V/ns
$dv/dt^{(3)}$	MOSFET $dv/dt$ ruggedness	50	V/ns
$T_{stg}$	Storage temperature range	- 55 to 150	$^\circ\text{C}$
$T_j$	Operating junction temperature range		$^\circ\text{C}$

1. Pulse width limited by safe operating area.
2.  $I_{SD} \leq 34\text{ A}$ ,  $di/dt \leq 400\text{ A}/\mu\text{s}$ ;  $V_{DS\text{ peak}} < V_{(BR)DSS}$ ,  $V_{DD} = 400\text{ V}$ .
3.  $V_{DS} \leq 480\text{ V}$

**Table 3. Thermal data**

Symbol	Parameter	Value			Unit
		D <sup>2</sup> PAK	TO-220	TO-247	
$R_{thj-case}$	Thermal resistance junction-case	0.50			$^\circ\text{C}/\text{W}$
$R_{thj-pcb}$	Thermal resistance junction-pcb <sup>(1)</sup>	30			$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal resistance junction-ambient		62.5	50	$^\circ\text{C}/\text{W}$

1. When mounted on 1 inch<sup>2</sup> FR-4, 2 Oz copper board

**Table 4. Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}$	Avalanche current, repetitive or not repetitive (pulse width limited by $T_{jmax}$ )	6	A
$E_{AS}$	Single pulse avalanche energy (starting $T_j = 25\text{ }^\circ\text{C}$ , $I_D = I_{AR}$ ; $V_{DD} = 50\text{ V}$ )	500	mJ

## 2 Electrical characteristics

( $T_C = 25\text{ °C}$  unless otherwise specified)

**Table 5. On /off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0, I_D = 1\text{ mA}$	600			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0, V_{DS} = 600\text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0, V_{DS} = 600\text{ V}, T_C = 125\text{ °C}^{(1)}$			100	$\mu\text{A}$
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0, V_{GS} = \pm 25\text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2	3	4	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}, I_D = 17\text{ A}$		0.078	0.088	$\Omega$

1. Defined by design, not subject to production test

**Table 6. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100\text{ V}, f = 1\text{ MHz}, V_{GS} = 0$	-	2500	-	pF
$C_{oss}$	Output capacitance		-	117	-	pF
$C_{rss}$	Reverse transfer capacitance		-	2.4	-	pF
$C_{oss\text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0\text{ to }480\text{ V}, V_{GS} = 0$	-	342	-	pF
$R_G$	Intrinsic gate resistance	$f = 1\text{ MHz}, I_D = 0$	-	4.4	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 480\text{ V}, I_D = 34\text{ A}, V_{GS} = 10\text{ V}$ (see <a href="#">Figure 17</a> )	-	57	-	nC
$Q_{gs}$	Gate-source charge		-	10	-	nC
$Q_{gd}$	Gate-drain charge		-	25.5	-	nC

1.  $C_{oss\text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

Table 7. Switching times

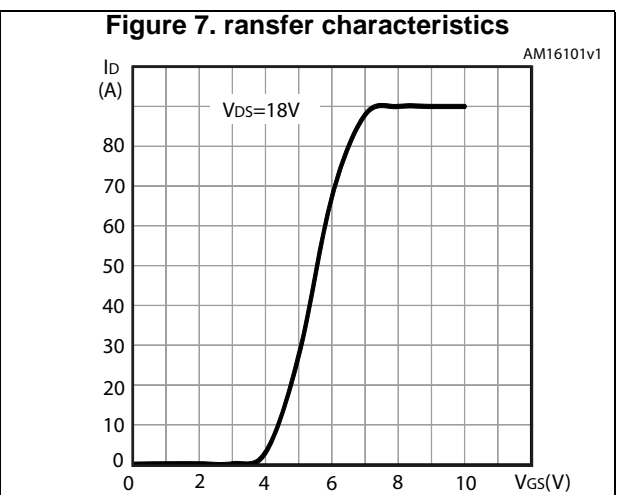
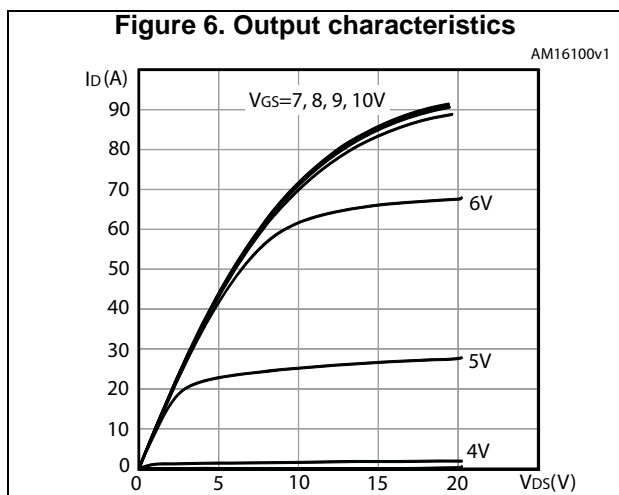
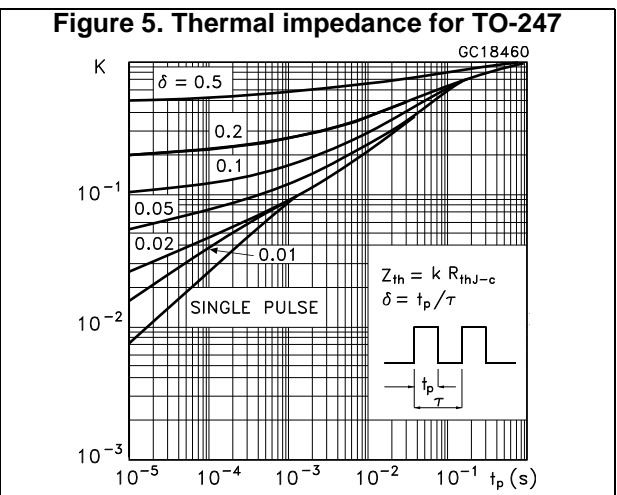
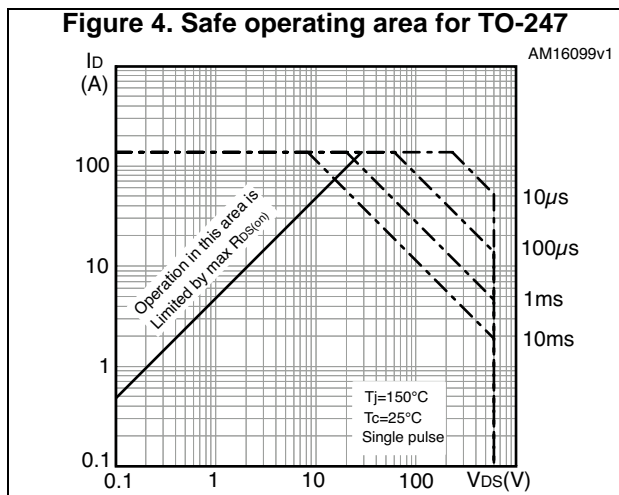
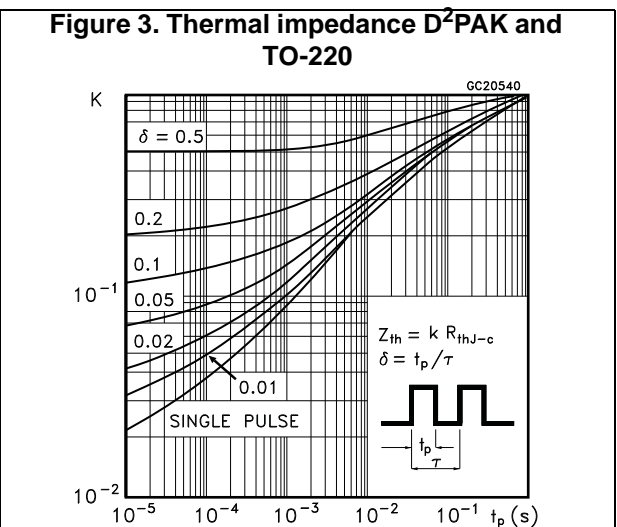
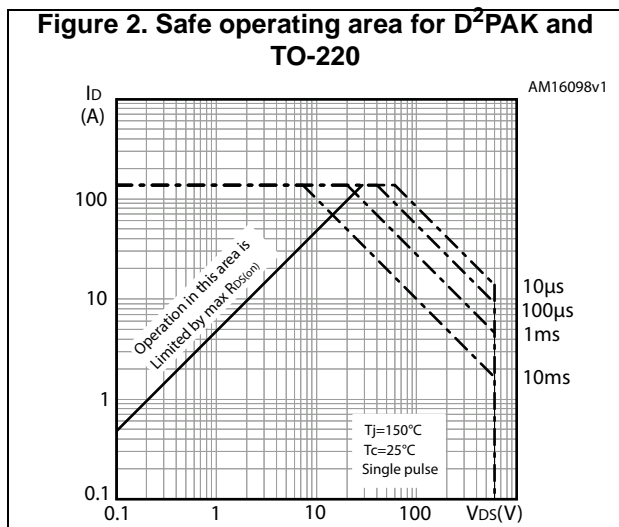
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300\text{ V}$ , $I_D = 34\text{ A}$ , $R_G = 4.7\ \Omega$ , $V_{GS} = 10\text{ V}$ (see <a href="#">Figure 16</a> and <a href="#">Figure 21</a> )	-	20.5	-	ns
$t_r$	Rise time		-	13.5	-	ns
$t_{d(off)}$	Turn-off-delay time		-	96	-	ns
$t_f$	Fall time		-	11	-	ns

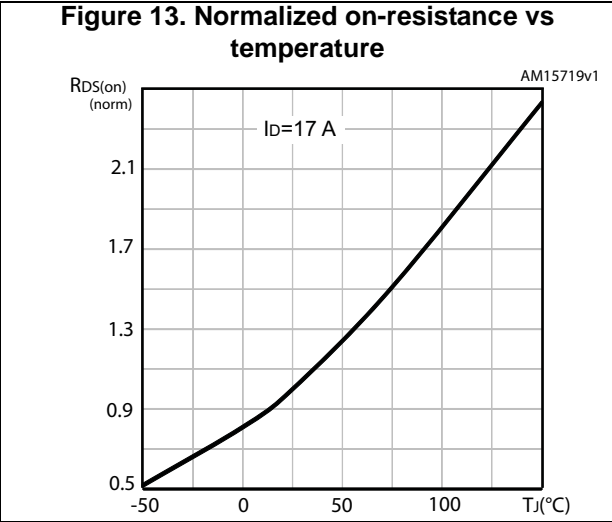
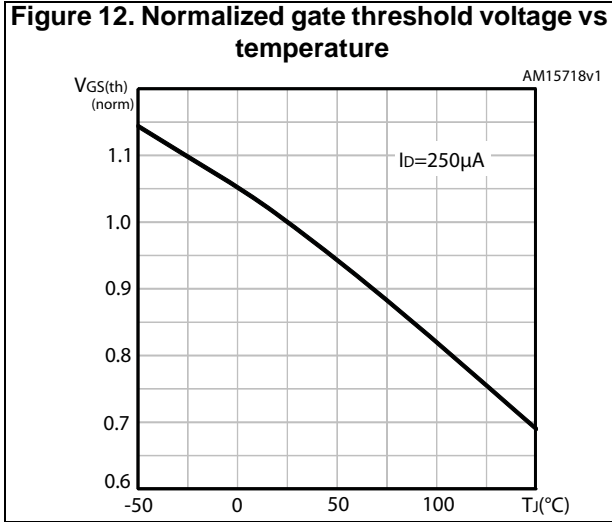
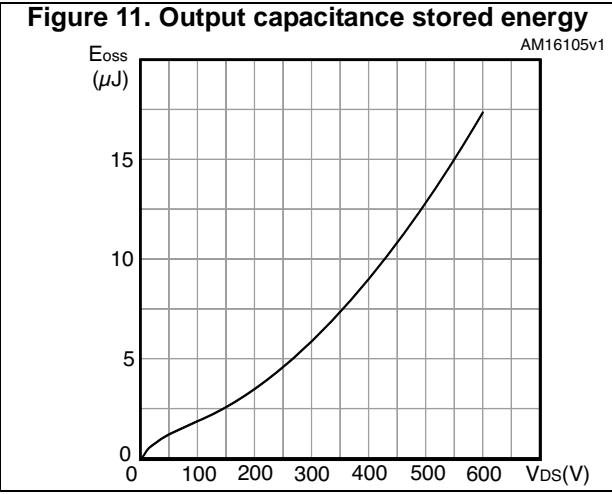
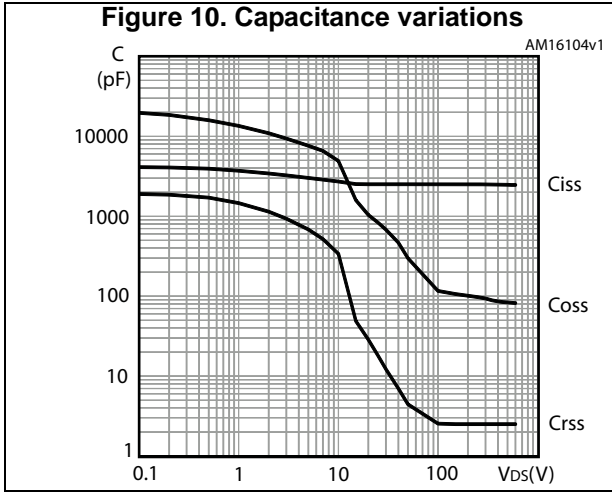
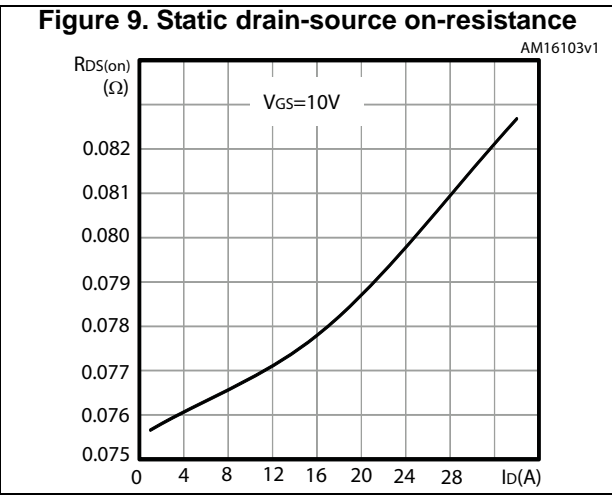
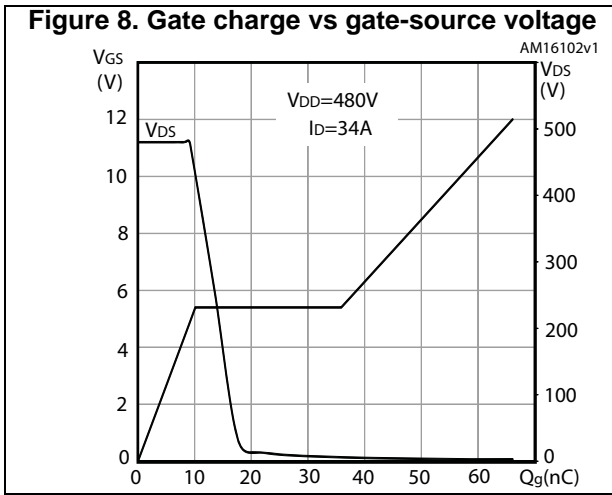
Table 8. Source drain diode

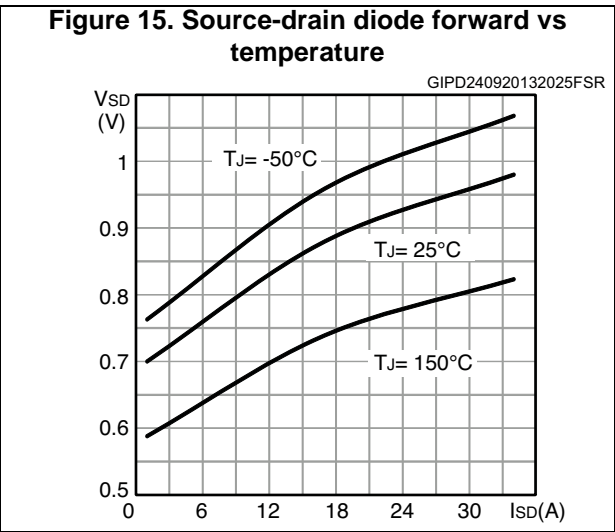
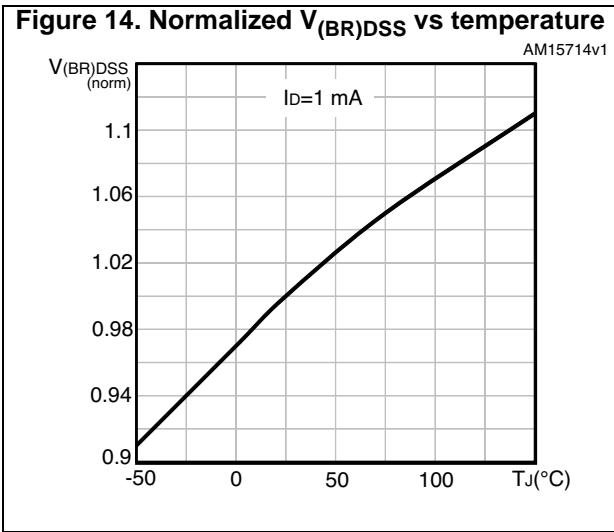
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-	34		A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-	136		A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 34\text{ A}$ , $V_{GS} = 0$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 34\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 60\text{ V}$ (see <a href="#">Figure 18</a> )	-	440		ns
$Q_{rr}$	Reverse recovery charge		-	8.2		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	37		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 34\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 60\text{ V}$ , $T_j = 150\text{ }^\circ\text{C}$ (see <a href="#">Figure 18</a> )	-	568		ns
$Q_{rr}$	Reverse recovery charge		-	11.5		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	40.5		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

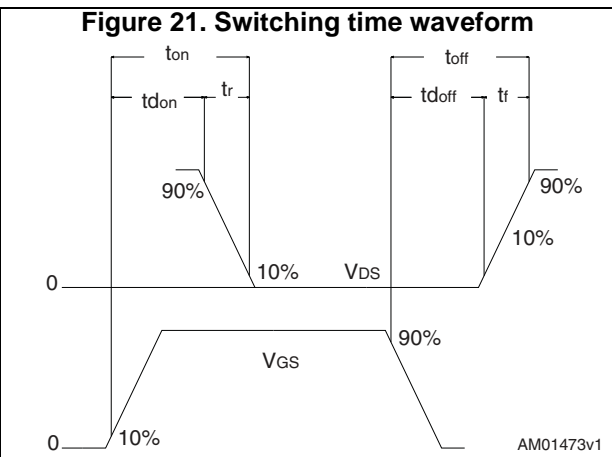
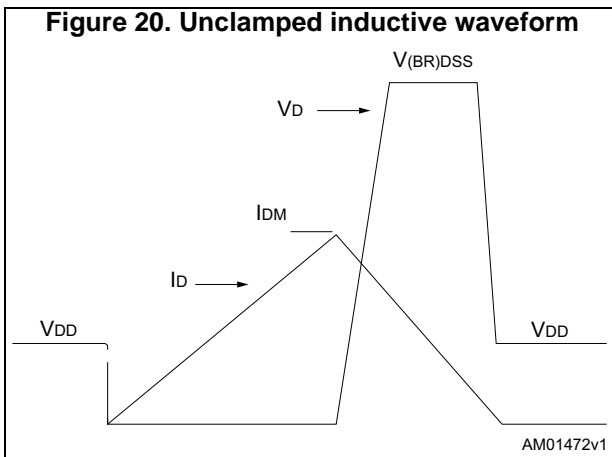
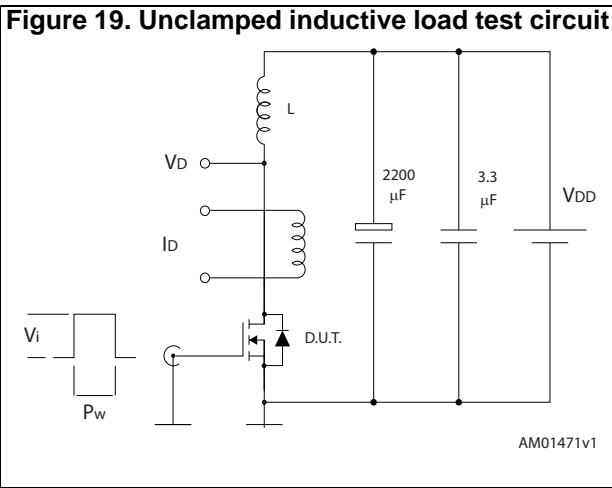
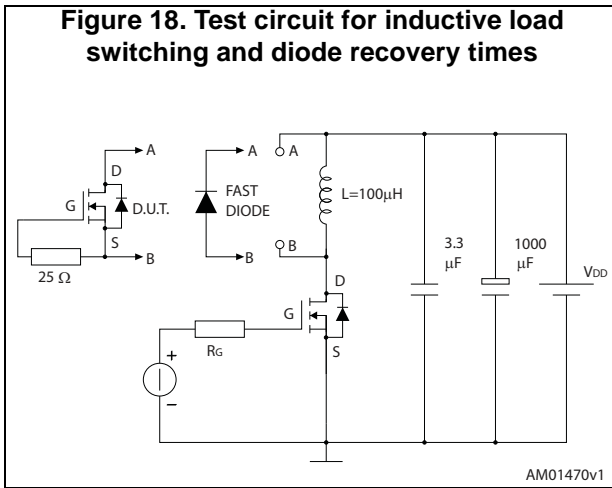
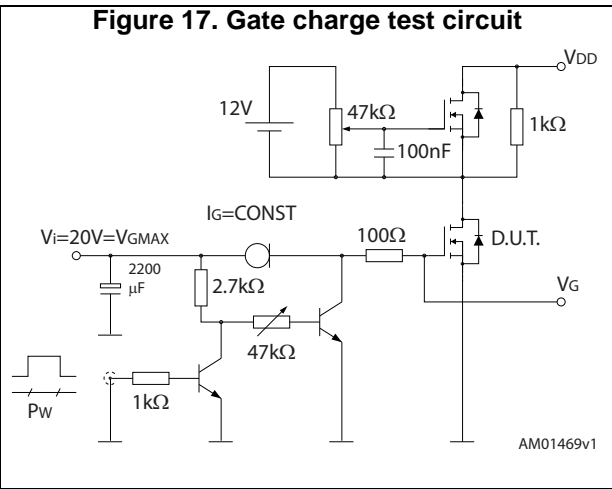
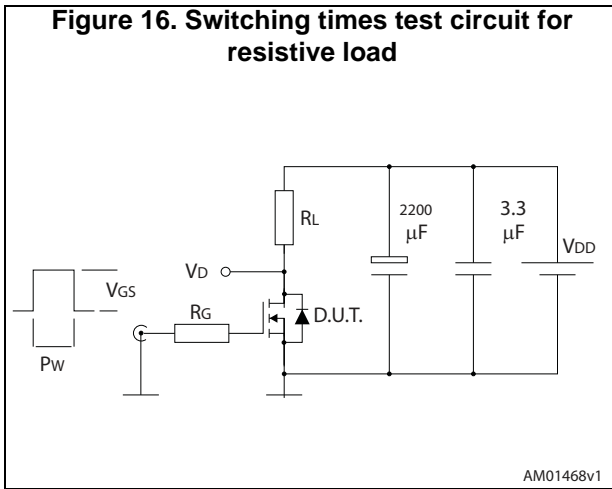








### 3 Test circuits

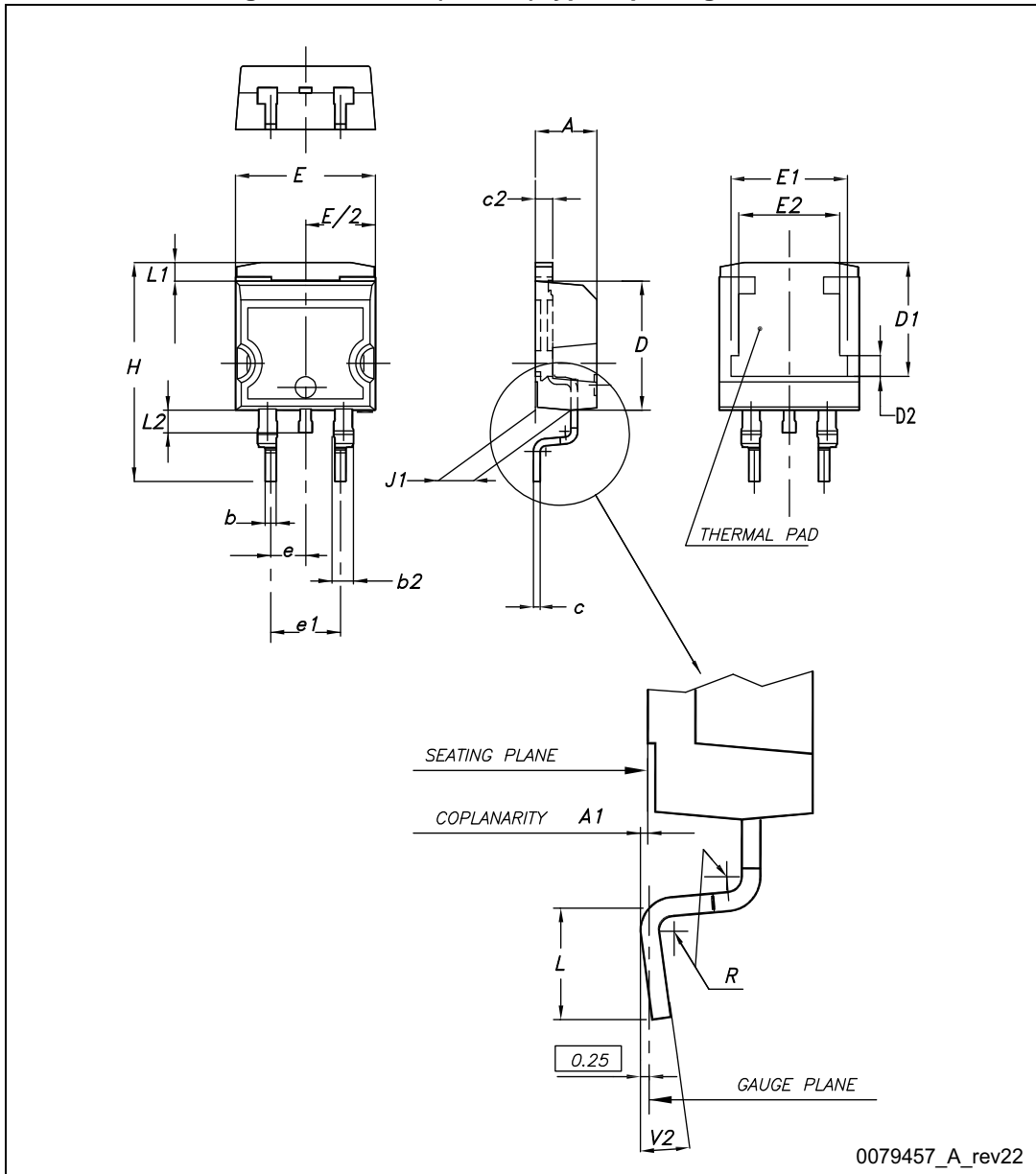


## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK<sup>®</sup> is an ST trademark.

### 4.1 D<sup>2</sup>PAK (TO-263) package information

Figure 22. D<sup>2</sup>PAK (TO-263) type A package outline

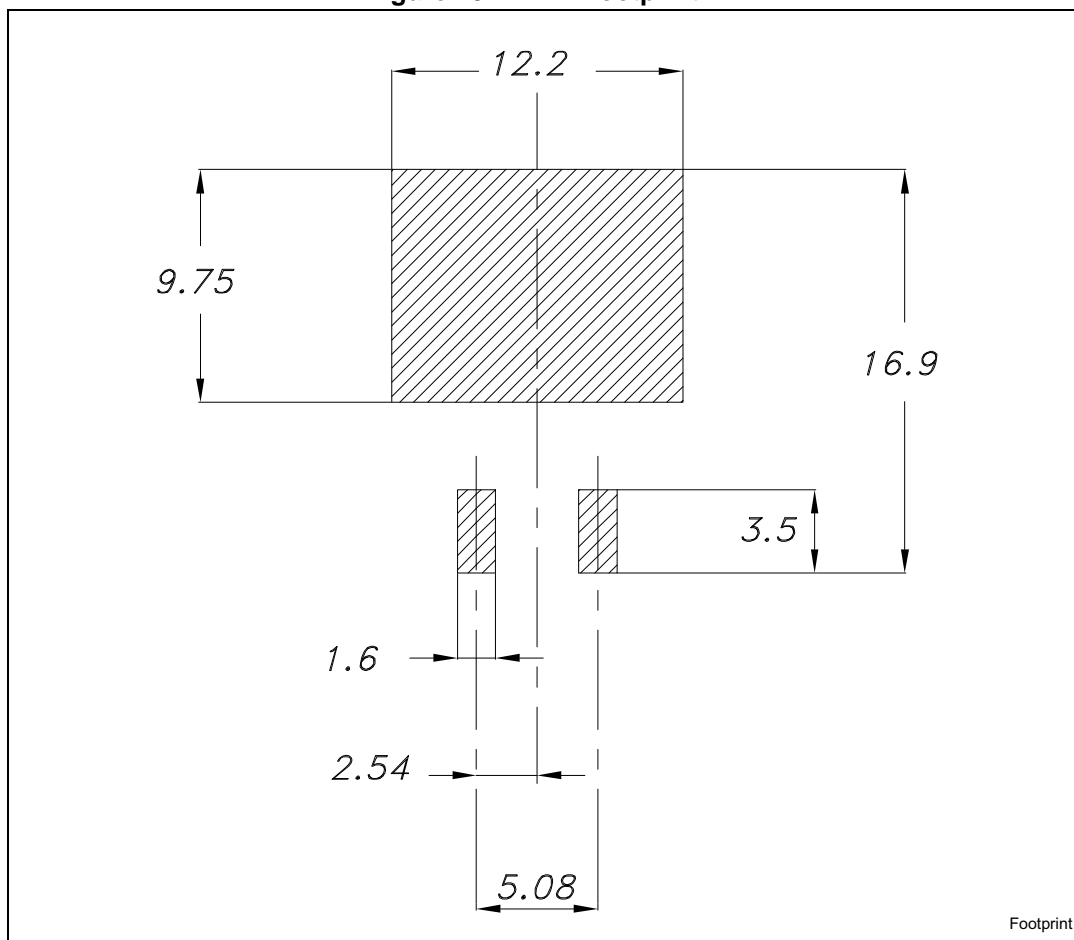


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Table 9. D<sup>2</sup>PAK (TO-263) type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.50	8.70	8.90
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

Figure 23. D<sup>2</sup>PAK footprint<sup>(a)</sup>



a. All dimension are in millimeters

## 4.2 TO-220 package information

Figure 24. TO-220 type A package outline

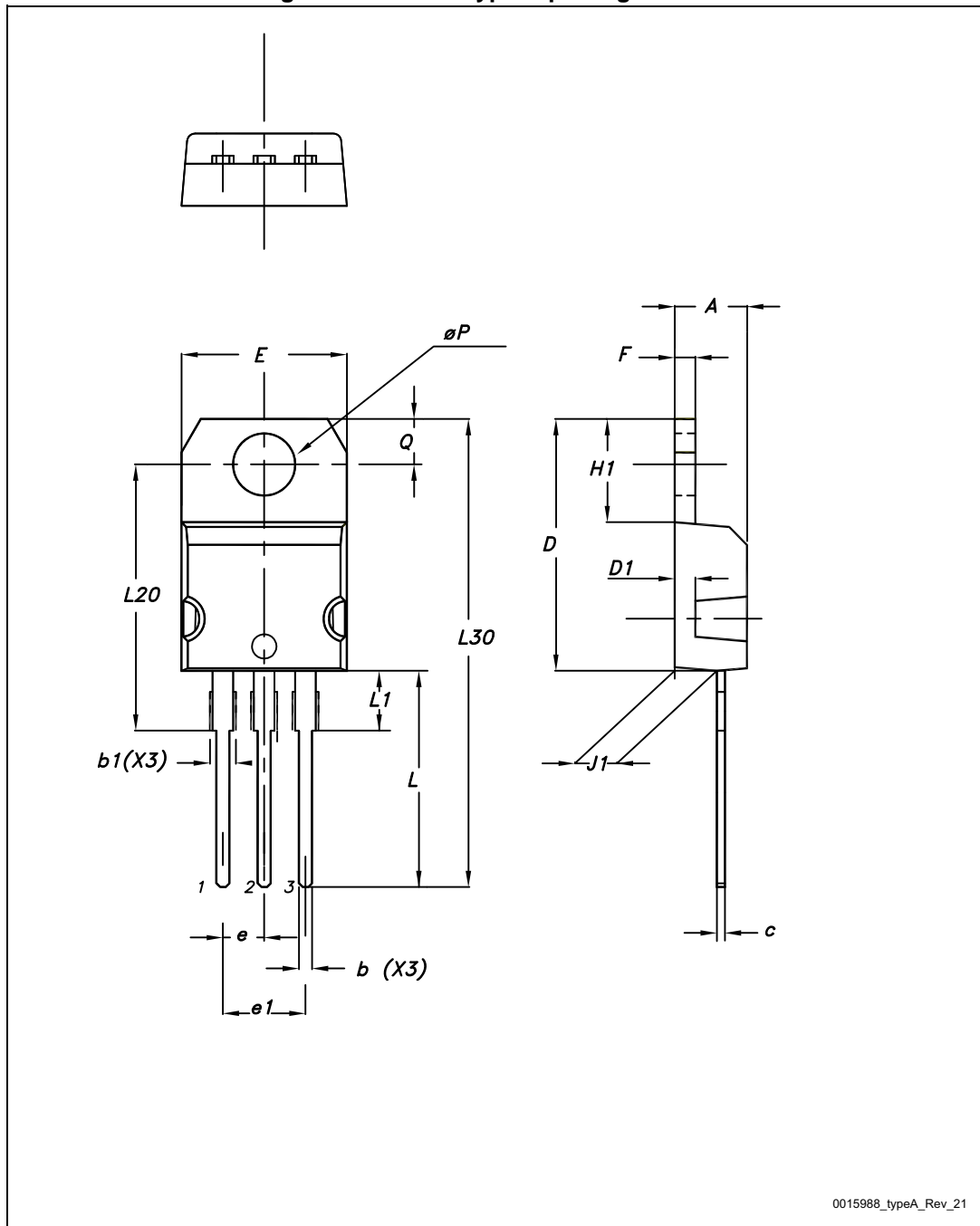


Table 10. TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

### 4.3 TO-247 package information

Figure 25. TO-247 package outline

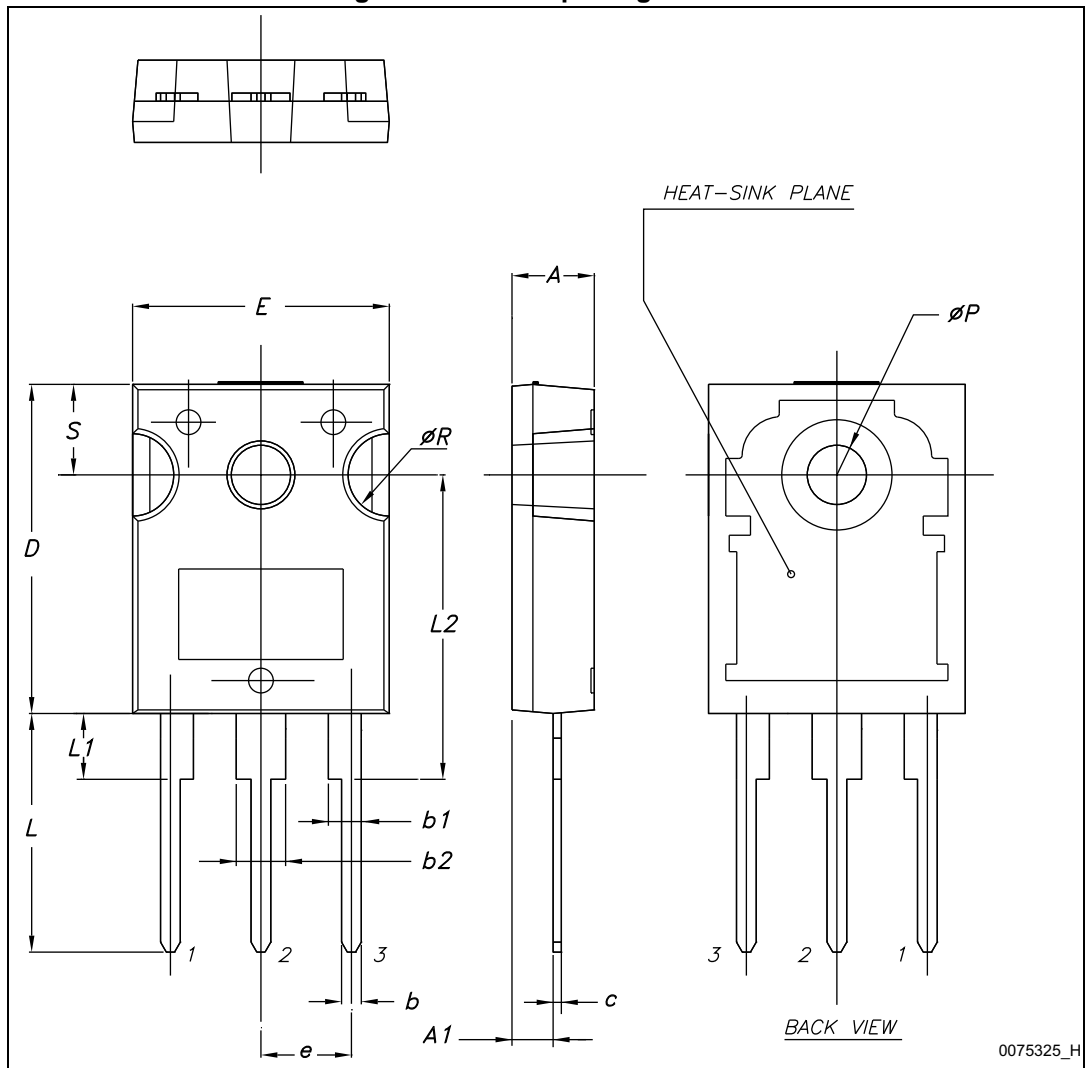




Table 11. TO-247 package mechanical data

Dim.	mm.		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

# 5 Packing information

Figure 26. Tape

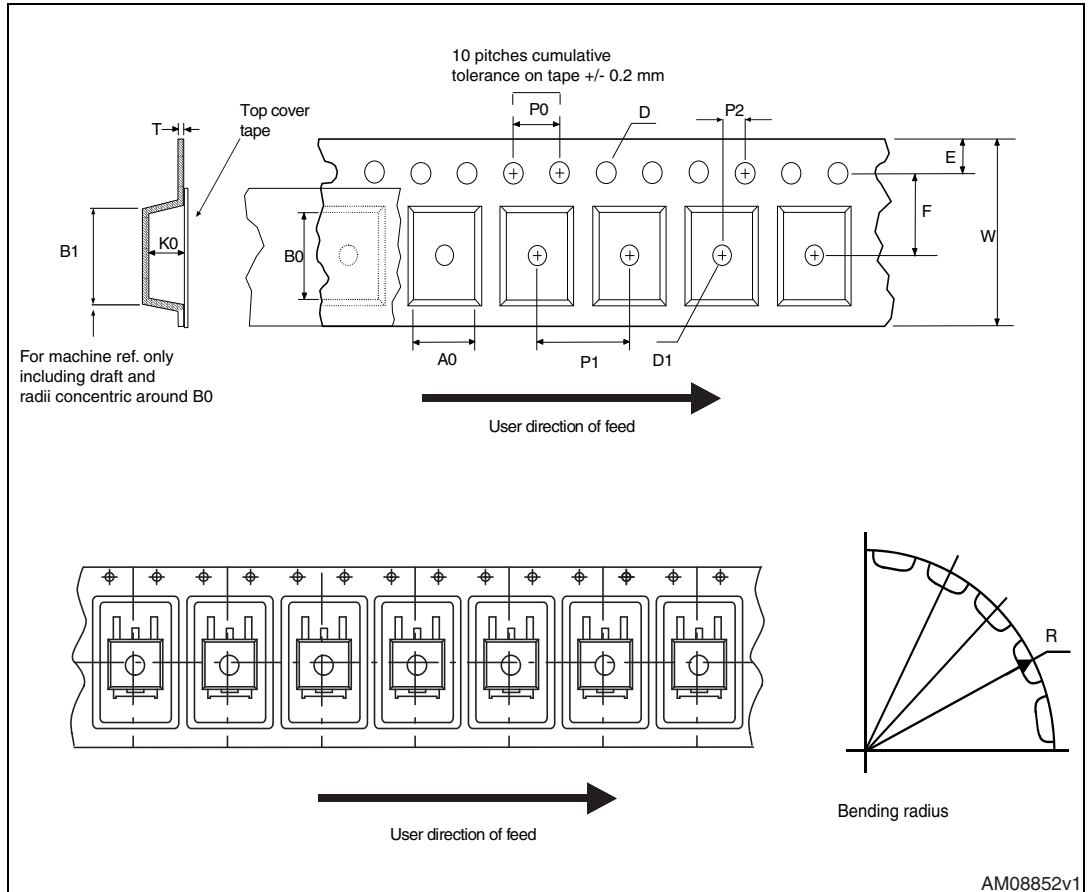
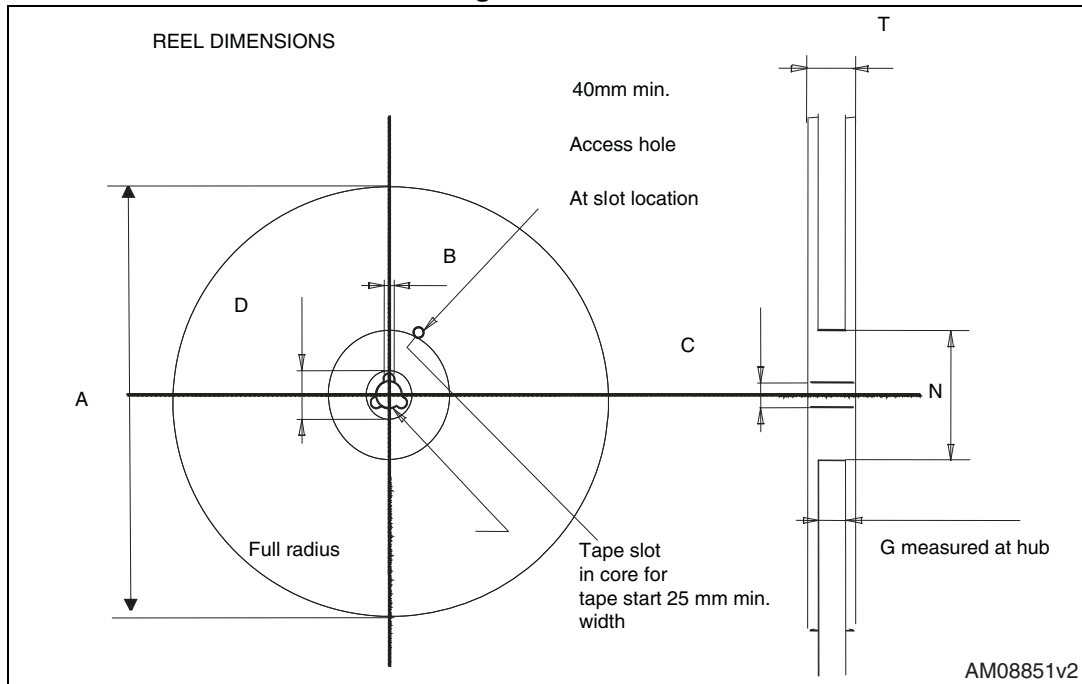


Figure 27. Reel



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Table 12. D<sup>2</sup>PAK (TO-263) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1		Base qty	1000
P2	1.9	2.1		Bulk qty	1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

## 6 Revision history

**Table 13. Document revision history**

Date	Revision	Changes
01-Jul-2013	1	First release.
23-Sep-2013	2	<ul style="list-style-type: none"> <li>– Added: TO-220FP and I<sup>2</sup>PAKFP packages</li> <li>– Inserted: <math>V_{ISO}</math> in <i>Table 2</i></li> <li>– Modified: values in <i>Table 4</i>, the entire typical values in <i>Table 6</i>, <i>7</i> and <i>8</i></li> <li>– Updated: <i>Section 4: Package mechanical data</i>.</li> <li>– Minor text changes</li> </ul>
13-May-2014	3	<ul style="list-style-type: none"> <li>– The part numbers STP40N60M2 and STW40N60M2 have been moved to a separate datasheet</li> <li>– Minor text changes</li> </ul>
09-Aug-2016	4	<p>Updated title, features and description in cover page.</p> <p>Updated <i>Table 2: Absolute maximum ratings</i>, <i>Table 5: On /off states</i> and <i>Table 8: Source drain diode</i>.</p> <p>Updated <i>Section 4.1: D<sup>2</sup>PAK (TO-263) package information</i> and <i>Section 4.2: TO-220 package information</i>.</p> <p>Minor text changes.</p>

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